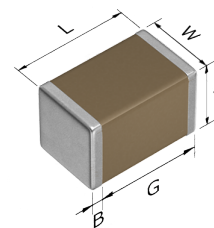


# 积层贴片陶瓷片式电容器

C2012X7R1H225K125AC

RoHS Reach Halogen Free Pb Free

|      |   |
|------|---|
| 交货型号 | C2012X7R1H225KT****                                   |
| 用途   | 一般等级<br>车载用途时为 <a href="#">CGA4J3X7R1H225K125AB</a> 。 |
| 特点   | <b>General</b> 一般 (~75V)                              |
| 系列   | C2012 [EIA 0805]                                      |
| 状态   | 量产体制  |



## 尺寸

|            |  |
|------------|--|
| 长度(L)      | 2.00mm ±0.20mm   |
| 宽度(W)      | 1.25mm ±0.20mm   |
| 厚度(T)      | 1.25mm ±0.20mm   |
| 端子宽度(B)    | 0.20mm Min.  |
| 端子间隔(G)    | 0.50mm Min.  |
| 推荐焊盘布局(PA) | 1.00mm to 1.30mm(Flow Soldering)<br>0.90mm to 1.20mm(Reflow Soldering) |
| 推荐焊盘布局(PB) | 1.00mm to 1.20mm(Flow Soldering)<br>0.70mm to 0.90mm(Reflow Soldering) |
| 推荐焊盘布局(PC) | 0.80mm to 1.10mm(Flow Soldering)<br>0.90mm to 1.20mm(Reflow Soldering) |

## 电气特性

|             |             |
|-------------|-------------|
| 电容          | 2.2 μF ±10% |
| 额定电压        | 50VDC       |
| 温度特性        | X7R(±15%)   |
| 耗散因数 (Max.) | 5%          |
| 绝缘电阻 (Min.) | 227MΩ       |

## 其他

|          |                |
|----------|----------------|
| 焊接方法     | 流体<br>回流       |
| AEC-Q200 | NO             |
| 包装形式     | 塑封编带 (180mm卷筒) |
| 包装个数     | 2000pcs        |

! Images are for reference only and show exemplary products.

! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

特性图表 (这是参考数据，并不保证产品的特性。)

## Associated Images

